1. Name of conveying party(ies):
   (a) Yoon, Mee-Young
   (b) Lee, Sang-In;
   (c) Lim, Hyun-Seok

Additional name(s) of conveying party(ies) attached?  [ ] Yes  [X] No

3. Nature of Conveyance:
   [X] Assignment  [ ] Merger
   [ ] Security Agreement  [ ] Change of Name
   [ ] Other

Execution Date:  (a) September 16, 1999;  (b) & (c) September 15, 1999

4. Application number(s) or patent number(s):
   If this document is being filed together with a new application, the execution date of the application is:  (a) September 16, 1999;  (b) & (c) September 15, 1999

A. Patent Application No.(s) - 09/297616
   Title: Semiconductor Device Fabrication Method Using An Interface Control Layer To Improve A Metal Interconnection Layer

B. Patent No.(s)

Additional numbers attached?  [ ] Yes  [X] No

5. Name and address of party to whom correspondence concerning document should be mailed:
   Name: David T. Millers
   Internal Address: SKJERVEN, MORRILL, MacPHERSON, FRANKLIN & FRIEL LLP
   Street Address: 25 METRO DRIVE, SUITE 700
   City SAN JOSE  State CA  ZIP 95110

6. Total number of applications and patents involved:  1

7. Total fee (37 CFR 3.41): $40.00
   [X] Authorized to be charged to Deposit Account 19-2386
   [X] Charge Deposit Account 19-2386 for any additional fees required for this conveyance and credit deposit account 19-2386 any amounts overpaid

8. Statement and signature.
   To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

   [Signature]

Name of Person Signing  9-16-99

Total number of pages comprising cover sheet: 1

PATENT
REEL: 010260 FRAME: 0544
ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Mee-Young Yoon of 506-1703, Mujigae Maeul Chonggu Apt., 221, Bundang-gu, Seongnam-city, Kyungki-do, Republic of Korea

Sang-In Lee of 104-706, hanguk 1-cha Apt., Maelan 2-dong, Paldal-gu, Suwon-city, Kyungkido, Republic of Korea

Hyun-Seok Lim of San 7-1, Nongseco-ri, Kiheung-eub, Yongin-city, Kyungki-do, Republic of Korea

hereby sell, assign and transfer to Samsung Electronics Co., Ltd., a Korean corporation, having a place of business at 416, Maelan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea, its successors and assigns, the entire right, title and interest throughout the world in our invention in

Semiconductor Device Fabrication Method Using An Interface Control Layer To Improve A Metal Interconnection Layer

for which we have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 16 day of September, 1999.

Mee-Young Yoon

Executed this ___ day of ______________________, 1999.

Sang-in Lee

Executed this ___ day of ______________________, 1999.

Hyun-seok Lim
ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Mee-Young Yoon of 506-1703, Mullaeae Masul Chonggu Apts., 221, Bundang-gu, Seongnam-city
Kyungki-do, Republic of Korea

Sang-In Lee of 104-706, honguk 1-chon Apts., Maesan
2-dong, Paldal-gu, Suwon-city
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Cheo I Lee
of San 7-1, Nongseo-ri, Kihung-eub, Yongin-city,
Kyungki-do, Republic of Korea

Hyun-Sook Lim

hereby sell, assign and transfer to Samsung Electronics Co., Ltd., a Korean corporation, having a place of business at
416, Maesan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea, its successors and assigns, the entire
right, title and interest throughout the world in our invention in

Semiconductor Device Fabrication Method Using An Interface Control Layer To
Improve A Metal Interconnection Layer

for which we have executed a United States patent application on or about the date of this assignment, and all patent
applications and patents of every country for said invention, including divisions, reissues, continuations and
extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-
named assignee to apply for patents in foreign countries for said invention, and to claim all rights of priority without
further authorization from us; we agree to execute all papers useful in connection with said United States and foreign
applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at
their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request the
Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee,
its successors and assigns.

Executed this ___ day of _______________, 1999.

______________________________
Mee-Young Yoon

Executed this 14th day of Sep., 1999.

______________________________
Sang-In Lee

Executed this 15th day of September, 1999.

______________________________
Hyun-Sook Lim